


## Full Material Declaration for attached parts list

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	<p><b>Diotec Semiconductor AG</b>  DUNS number: 330866844  -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany  Declarations authorised by:  Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 02 January 2014 [Approved on 25 July 2025, 19:46 GMT]

## Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.29%	Silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	69%	Carbon black	1333-86-4	0.8%
			Silicon Dioxide	7631-86-9	2.5%
			phenolic epoxy resin	61788-97-4	3.7%
			ALUMINUM(III) HYDROXIDE	21645-51-2	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	6%
			Quartz sand	60676-86-0	82%
Inner preparation	Copper alloys	0.13%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.61%	Tin elemental	7440-31-5	100%
Leadframe	Nickel and Nickel alloys	28.97%	Copper	7440-50-8	0.381%
			SILVER, ELEMENTAL	7440-22-4	1.548%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.071%

## Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-23/TO-236_Pb&H-free_(H)_sin.	Diode / Transistor SMD	0.01	g

